



## DRV5033-Q1 Automotive Digital-Omnipolar-Switch Hall Effect Sensor

### 1 Features

- Digital Omnipolar-Switch Hall Sensor
- AEC-Q100 Qualified for Automotive Applications
  - Grade 1:  $T_A = -40$  to  $125^\circ\text{C}$  (Q, See [Figure 22](#))
  - Grade 0:  $T_A = -40$  to  $150^\circ\text{C}$  (E, See [Figure 22](#))
- Superior Temperature Stability
  - $B_{OP} \pm 10\%$  Over Temperature
- High Sensitivity ( $B_{OP}$  and  $B_{RP}$ )
  - $\pm 6.9 / \pm 3.5$  mT (AJ)
- Detects North and South Magnetic Field
- Supports a Wide Voltage Range
  - 2.7 to 38 V
  - No External Regulator Required
- Open Drain Output (30-mA Sink)
- Fast 35- $\mu\text{s}$  Power-On Time
- Small Package and Footprint
  - Surface Mount 3-Pin SOT-23 (DBZ)
    - $2.92\text{ mm} \times 2.37\text{ mm}$
  - Through-Hole 3-Pin SIP (LPG)
    - $4.00\text{ mm} \times 3.15\text{ mm}$
- **Protection Features**
  - Reverse Supply Protection (up to  $-22\text{ V}$ )
  - Supports up to 40-V Load Dump
  - Output Short-Circuit Protection
  - Output Current Limitation
  - OUT Short to Battery Protection

### 2 Applications

- Docking Detection
- Door Open and Close Detection
- Proximity Sensing
- Valve Positioning
- Pulse Counting

### 3 Description

The DRV5033-Q1 device is a chopper-stabilized Hall Effect Sensor that offers a magnetic sensing solution with superior sensitivity stability over temperature and integrated protection features.

The DRV5033-Q1 responds the same to both polarities of magnetic field direction. When the applied magnetic flux density exceeds the  $B_{OP}$  threshold, the DRV5033-Q1 open drain output goes low. The output stays low until the field decreases to less than  $B_{RP}$ , and then the output goes to high impedance. The output current sink capability is 30 mA. A wide operating voltage range from 2.7 to 38 V with reverse polarity protection up to  $-22\text{ V}$  makes the device suitable for a wide range of automotive applications.

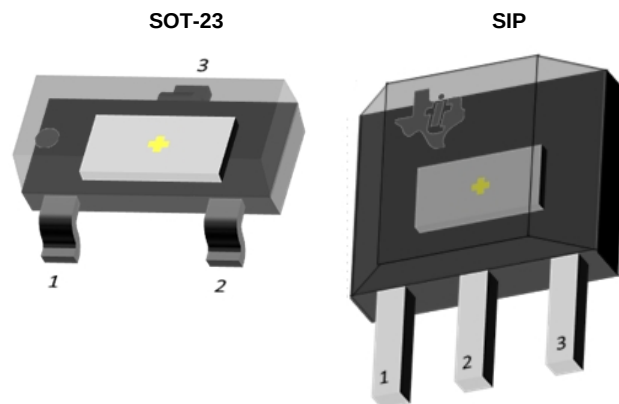
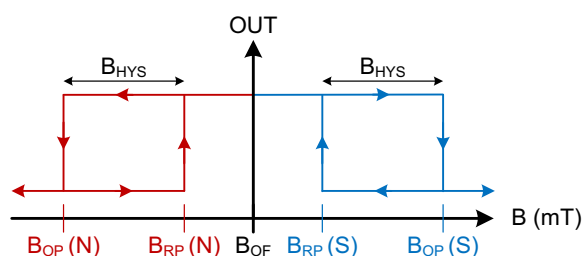
Internal protection functions are provided for reverse supply conditions, load dump, and output short circuit or over current.

#### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE    | BODY SIZE (NOM)                        |
|-------------|------------|----------------------------------------|
| DRV5033-Q1  | SOT-23 (3) | $2.92\text{ mm} \times 2.37\text{ mm}$ |
|             | SIP (3)    | $4.00\text{ mm} \times 3.15\text{ mm}$ |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Output State



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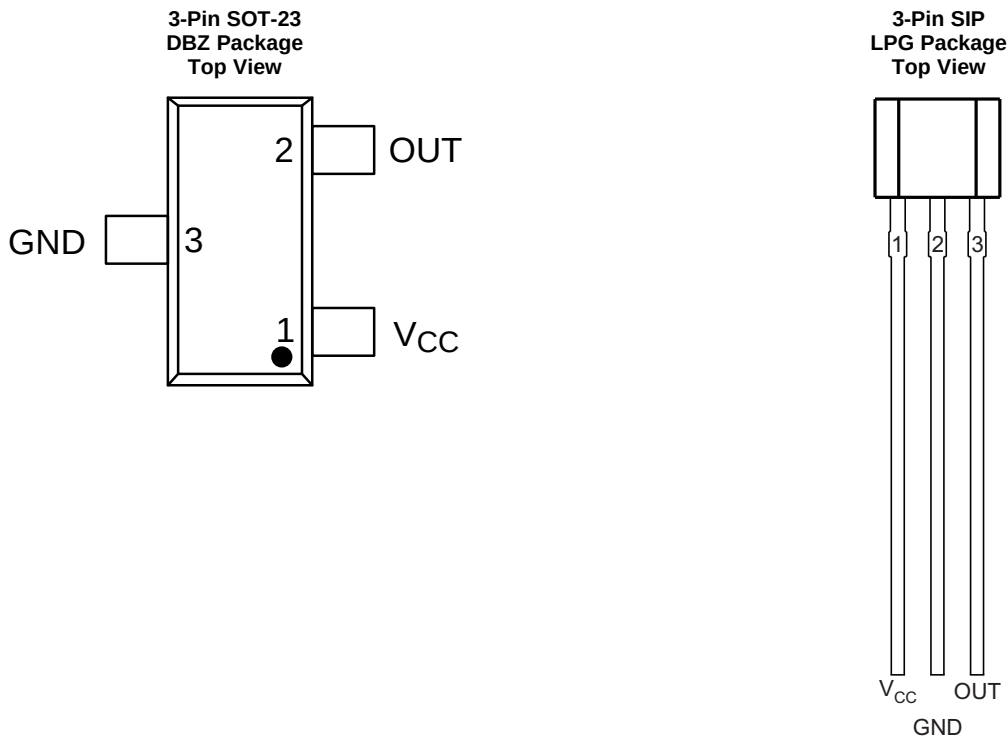
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## 5 Revision History

| Changes from Original (December 2014) to Revision A | Page     |
|-----------------------------------------------------|----------|
| • Updated device status to production data .....    | <b>1</b> |

## 6 Pin Configuration and Functions

For additional configuration information, see [Device Markings](#) and [Mechanical, Packaging, and Orderable Information](#).



**Pin Functions**

| PIN             |     |     | TYPE   | DESCRIPTION                                                                                                                     |
|-----------------|-----|-----|--------|---------------------------------------------------------------------------------------------------------------------------------|
| NAME            | DBZ | LPG |        |                                                                                                                                 |
| GND             | 3   | 2   | GND    | Ground pin                                                                                                                      |
| OUT             | 2   | 3   | Output | Hall sensor open-drain output. The open drain requires a resistor pullup.                                                       |
| V <sub>CC</sub> | 1   | 1   | PWR    | 2.7 to 38 V power supply. Bypass this pin to the GND pin with a 0.01-μF (minimum) ceramic capacitor rated for V <sub>CC</sub> . |

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

|                                                            |                                                             | MIN                | MAX                | UNIT |
|------------------------------------------------------------|-------------------------------------------------------------|--------------------|--------------------|------|
| Power supply voltage                                       | V <sub>CC</sub>                                             | –22 <sup>(2)</sup> | 40                 | V    |
|                                                            | Voltage ramp rate (V <sub>CC</sub> ), V <sub>CC</sub> < 5 V | Unlimited          |                    | V/μs |
|                                                            | Voltage ramp rate (V <sub>CC</sub> ), V <sub>CC</sub> > 5 V | 0                  | 2                  |      |
| Output pin voltage                                         | OUT                                                         | –0.5               | 40                 | V    |
| Output pin reverse current during reverse supply condition | OUT                                                         | 0                  | 100                | mA   |
| Operating junction temperature, T <sub>J</sub>             | Q, see <a href="#">Figure 22</a>                            | –40                | 150 <sup>(3)</sup> | °C   |
|                                                            | E, see <a href="#">Figure 22</a>                            | –40                | 175 <sup>(4)</sup> |      |
| T <sub>stg</sub>                                           | Storage temperature                                         | –65                | 150                | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Ensured by design. Only tested to –20 V.
- (3) Tested in production to T<sub>A</sub> = 125°C.
- (4) Tested in production to T<sub>A</sub> = 150°C.

### 7.2 ESD Ratings

|                    |                         | VALUE                                                                                    | UNIT  |
|--------------------|-------------------------|------------------------------------------------------------------------------------------|-------|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>              | ±2500 |
|                    |                         | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> | ±500  |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

|                   |                                              | MIN                              | MAX | UNIT |
|-------------------|----------------------------------------------|----------------------------------|-----|------|
| V <sub>CC</sub>   | Power supply voltage                         | 2.7                              | 38  | V    |
| V <sub>O</sub>    | Output pin voltage (OUT)                     | 0                                | 38  | V    |
| I <sub>SINK</sub> | Output pin current sink (OUT) <sup>(1)</sup> | 0                                | 30  | mA   |
| T <sub>A</sub>    | Operating ambient temperature                | Q, see <a href="#">Figure 22</a> | –40 | 125  |
|                   |                                              | E, see <a href="#">Figure 22</a> | –40 | 150  |

- (1) Power dissipation and thermal limits must be observed

### 7.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                              | DRV5033-Q1 |        | UNIT |
|-------------------------------|----------------------------------------------|------------|--------|------|
|                               |                                              | DBZ        | LPG    |      |
|                               |                                              | 3 PINS     | 3 PINS |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 333.2      | 180    | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 99.9       | 98.6   | °C/W |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 66.9       | 154.9  | °C/W |
| Ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 4.9        | 40     | °C/W |
| Ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 65.2       | 154.9  | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                         | TEST CONDITIONS                   | MIN                                                                                | TYP | MAX | UNIT |     |    |
|-----------------------------------|-----------------------------------|------------------------------------------------------------------------------------|-----|-----|------|-----|----|
| POWER SUPPLIES (V <sub>CC</sub> ) |                                   |                                                                                    |     |     |      |     |    |
| V <sub>CC</sub>                   | V <sub>CC</sub> operating voltage | 2.7                                                                                |     | 38  | V    |     |    |
| I <sub>CC</sub>                   | Operating supply current          | V <sub>CC</sub> = 2.7 to 38 V, T <sub>A</sub> = 25°C                               |     | 2.7 | mA   |     |    |
|                                   |                                   | V <sub>CC</sub> = 2.7 to 38 V, T <sub>A</sub> = T <sub>A, MAX</sub> <sup>(1)</sup> |     | 3   |      | 3.6 |    |
| t <sub>on</sub>                   | Power-on time                     | 35                                                                                 |     | 50  | μs   |     |    |
| OPEN DRAIN OUTPUT (OUT)           |                                   |                                                                                    |     |     |      |     |    |
| r <sub>DS(on)</sub>               | FET on-resistance                 | V <sub>CC</sub> = 3.3 V, I <sub>O</sub> = 10 mA, T <sub>A</sub> = 25°C             |     | 22  | Ω    |     |    |
|                                   |                                   | V <sub>CC</sub> = 3.3 V, I <sub>O</sub> = 10 mA, T <sub>A</sub> = 125°C            |     | 36  |      | 50  |    |
| I <sub>lkg(off)</sub>             | Off-state leakage current         | Output Hi-Z                                                                        |     | 1   | μA   |     |    |
| PROTECTION CIRCUITS               |                                   |                                                                                    |     |     |      |     |    |
| V <sub>CCR</sub>                  | Reverse supply voltage            | –22                                                                                |     |     | V    |     |    |
| I <sub>OC</sub>                   | Overcurrent protection level      | OUT shorted V <sub>CC</sub>                                                        |     | 15  | 30   | 45  | mA |

(1) T<sub>A, MAX</sub> is 125°C for Q Grade 1 devices and 150°C for E Grade 0 devices (see [Figure 22](#))

## 7.6 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER               |                               | TEST CONDITIONS                                                | MIN | TYP | MAX | UNIT |
|-------------------------|-------------------------------|----------------------------------------------------------------|-----|-----|-----|------|
| OPEN DRAIN OUTPUT (OUT) |                               |                                                                |     |     |     |      |
| t <sub>d</sub>          | Output delay time             | B = B <sub>RP</sub> – 10 mT to B <sub>OP</sub> + 10 mT in 1 μs |     | 13  | 25  | μs   |
| t <sub>r</sub>          | Output rise time (10% to 90%) | R1 = 1 kΩ, C <sub>O</sub> = 50 pF, V <sub>CC</sub> = 3.3 V     |     | 200 |     | ns   |
| t <sub>f</sub>          | Output fall time (90% to 10%) | R1 = 1 kΩ, C <sub>O</sub> = 50 pF, V <sub>CC</sub> = 3.3 V     |     | 31  |     | ns   |

## 7.7 Magnetic Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                        | TEST CONDITIONS                                                                    | MIN | TYP  | MAX | UNIT <sup>(1)</sup> |
|----------------------------------|------------------------------------------------------------------------------------|-----|------|-----|---------------------|
| f <sub>BW</sub>                  | Bandwidth <sup>(2)</sup>                                                           | 20  |      |     | kHz                 |
| <b>DRV5033AJ: ±6.9 / ±3.5 mT</b> |                                                                                    |     |      |     |                     |
| B <sub>OP</sub>                  | Operate point; see <a href="#">Figure 12</a>                                       | ±3  | ±6.9 | ±12 | mT                  |
| B <sub>RP</sub>                  | Release point; see <a href="#">Figure 12</a>                                       | ±1  | ±3.5 | ±5  | mT                  |
| B <sub>hys</sub>                 | Hysteresis; B <sub>hys</sub> = (B <sub>OP</sub> – B <sub>RP</sub> ) <sup>(3)</sup> |     | 3.4  |     | mT                  |
| B <sub>O</sub>                   | Magnetic offset; B <sub>O</sub> = (B <sub>OP</sub> + B <sub>RP</sub> ) / 2         |     | 5.2  |     | mT                  |

(1) 1 mT = 10 Gauss

(2) Bandwidth describes the fastest changing magnetic field that can be detected and translated to the output.

(3) |B<sub>OP</sub>| is always greater than |B<sub>RP</sub>|.

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### 7.8 Typical Characteristics

$T_A > 125^\circ\text{C}$  data is valid for Grade 0 devices only (E, see Figure 22)

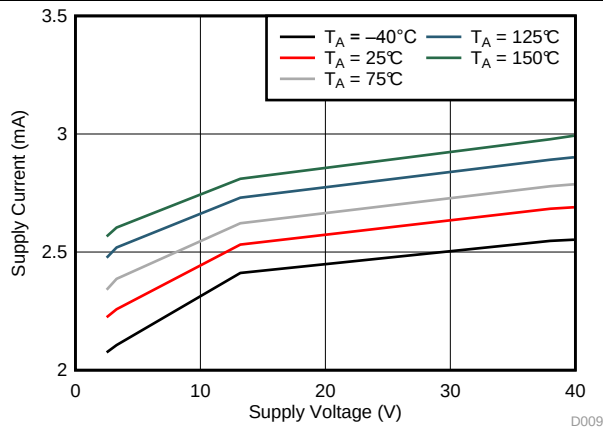


Figure 1.  $I_{CC}$  vs  $V_{CC}$

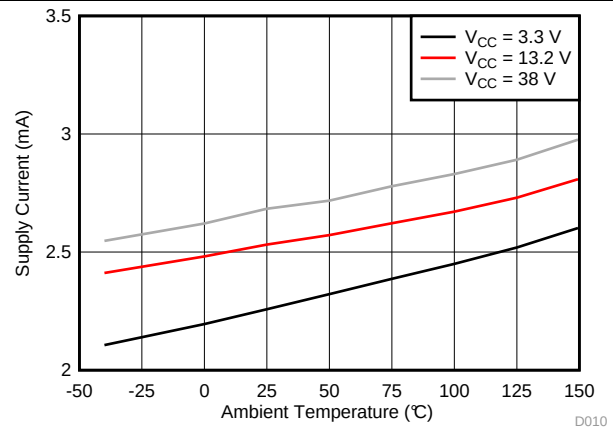


Figure 2.  $I_{CC}$  vs Temperature

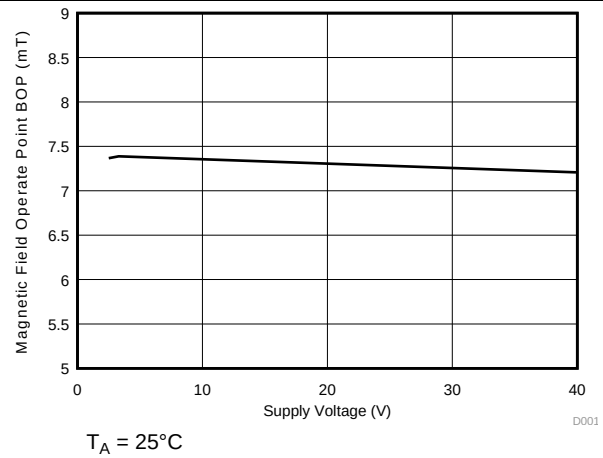


Figure 3. DRV5033-Q1AJ,  $B_{OP}$  vs  $V_{CC}$

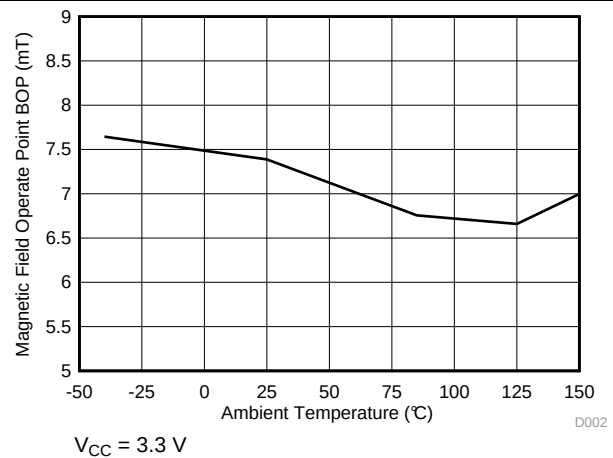


Figure 4. DRV5033-Q1AJ,  $B_{OP}$  vs Temperature

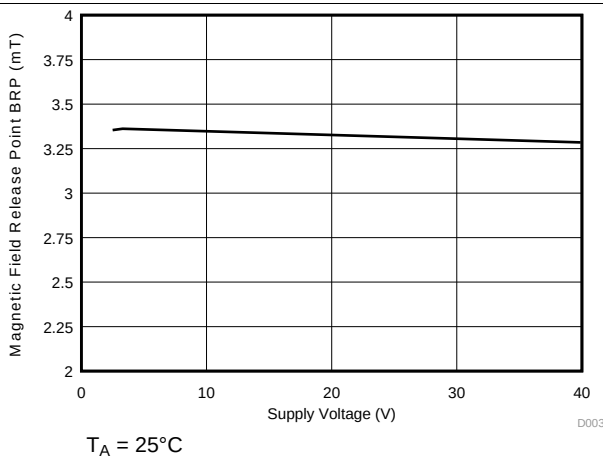


Figure 5. DRV5033-Q1AJ,  $B_{RP}$  vs  $V_{CC}$

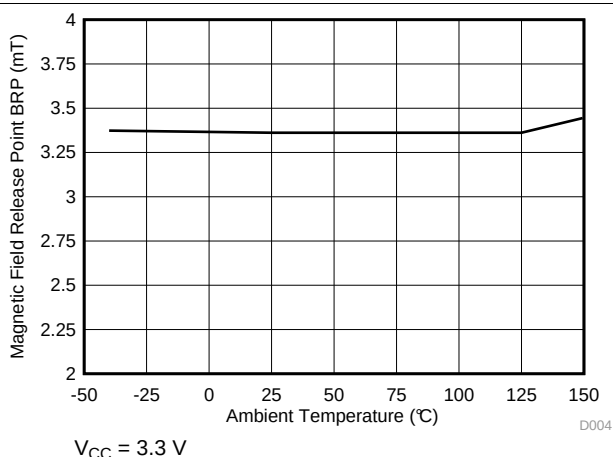
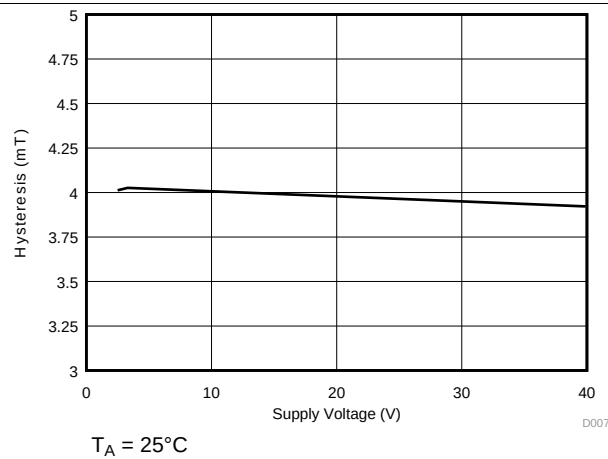


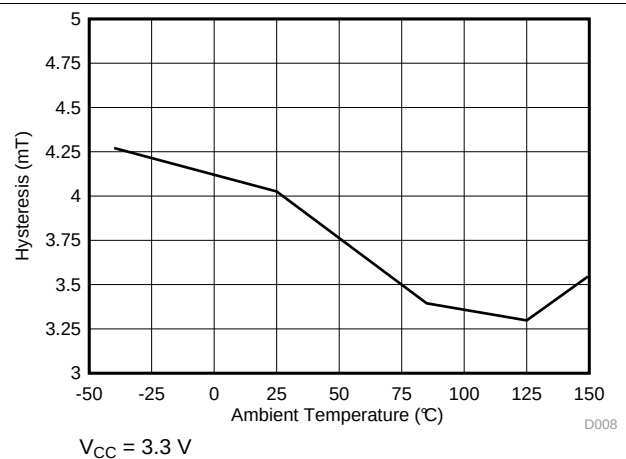
Figure 6. DRV5033-Q1AJ,  $B_{RP}$  vs Temperature

## Typical Characteristics (continued)

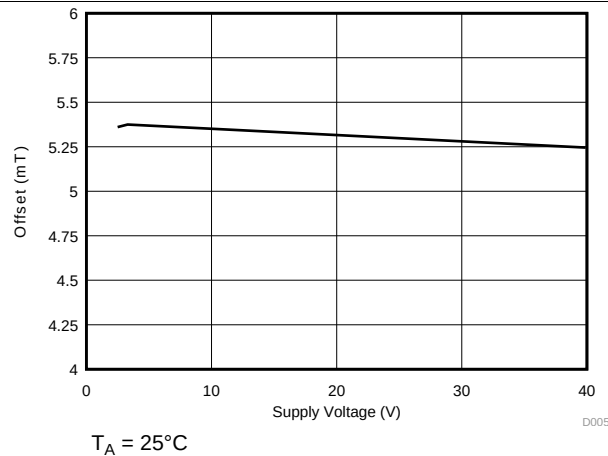
$T_A > 125^\circ\text{C}$  data is valid for Grade 0 devices only (E, see [Figure 22](#))



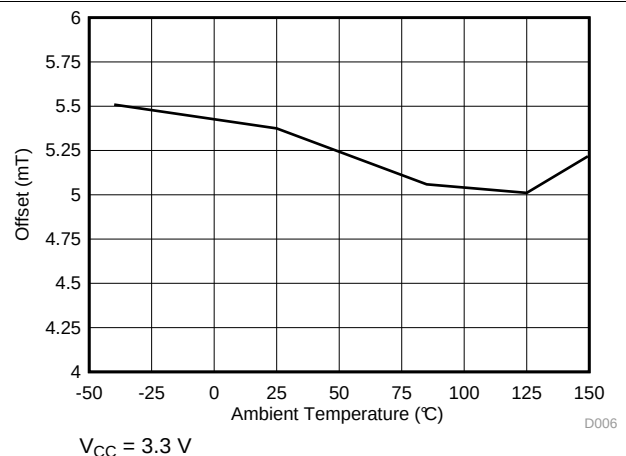
**Figure 7. DRV5033-Q1AJ, Hysteresis vs  $V_{CC}$**



**Figure 8. DRV5033-Q1AJ, Hysteresis vs Temperature**



**Figure 9. DRV5033-Q1AJ, Offset vs  $V_{CC}$**



**Figure 10. DRV5033-Q1AJ, Offset vs Temperature**

## 8 Detailed Description

### 8.1 Overview

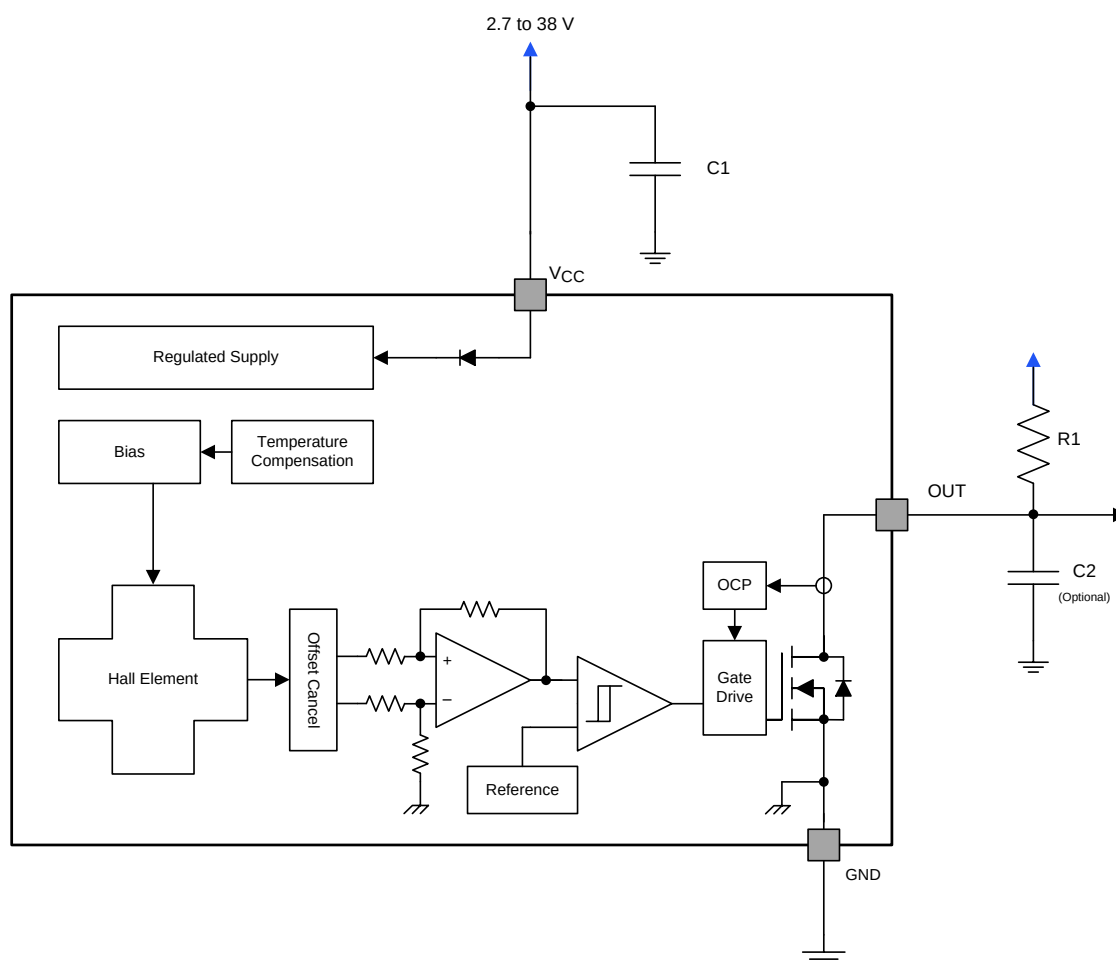
The DRV5033-Q1 device is a chopper-stabilized hall sensor with a digital omnipolar switch output for magnetic sensing applications. The DRV5033-Q1 device can be powered with a supply voltage between 2.7 and 38 V, and will survive  $-22$  V reverse battery conditions continuously. Note that the DRV5033-Q1 device will not be operating when about  $-22$  to  $2.4$  V is applied to  $V_{CC}$  (with respect to GND). In addition, the device can withstand voltages up to  $40$  V for transient durations.

The field polarity is defined as follows: a **south pole** near the marked side of the package is a **positive magnetic field**. A **north pole** near the marked side of the package is a **negative magnetic field**.

The omnipolar configuration allows the hall sensor to respond to either a south or north pole. A strong magnetic field of either polarity will cause the output to pull low (operate point,  $B_{OP}$ ), and a weaker magnetic field will cause the output to release (release point,  $B_{RP}$ ). Hysteresis is included in between the operate and release points, so magnetic field noise will not trip the output accidentally.

An external pullup resistor is required on the OUT pin. The OUT pin can be pulled up to  $V_{CC}$ , or to a different voltage supply. This allows for easier interfacing with controller circuits.

### 8.2 Functional Block Diagram





## 8.3 Feature Description

### 8.3.1 Field Direction Definition

A positive magnetic field is defined as a **south pole** near the marked side of the package as shown in Figure 11.

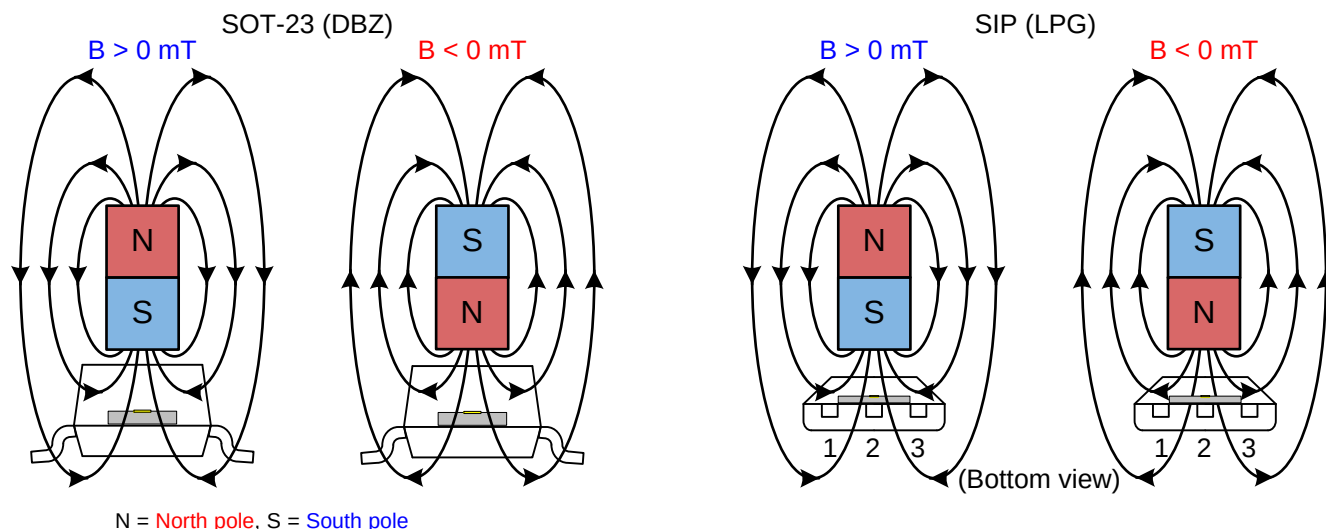


Figure 11. Field Direction Definition

### 8.3.2 Device Output

If the device is powered on with a magnetic field strength between  $B_{RP}$  and  $B_{OP}$ , then the device output is indeterminate and can either be Hi-Z or Low. If the field strength is greater than  $B_{OP}$ , then the output is pulled low. If the field strength is less than  $B_{RP}$ , then the output is released.

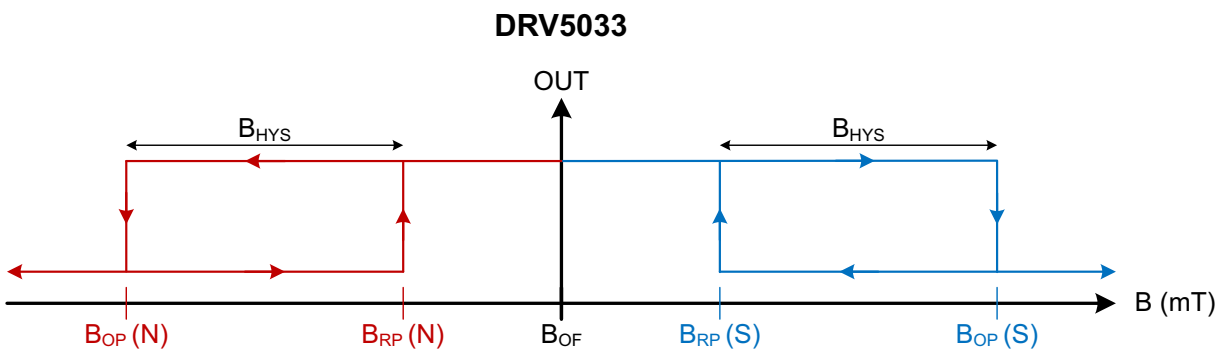
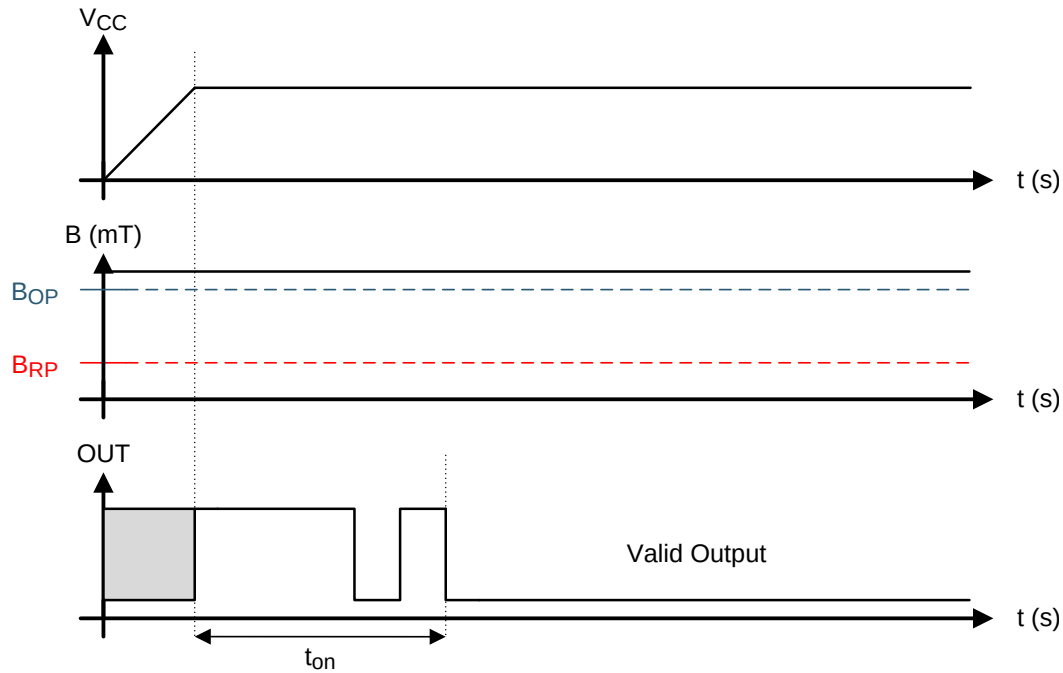


Figure 12. DRV5033-Q1— $B_{OP} > 0$

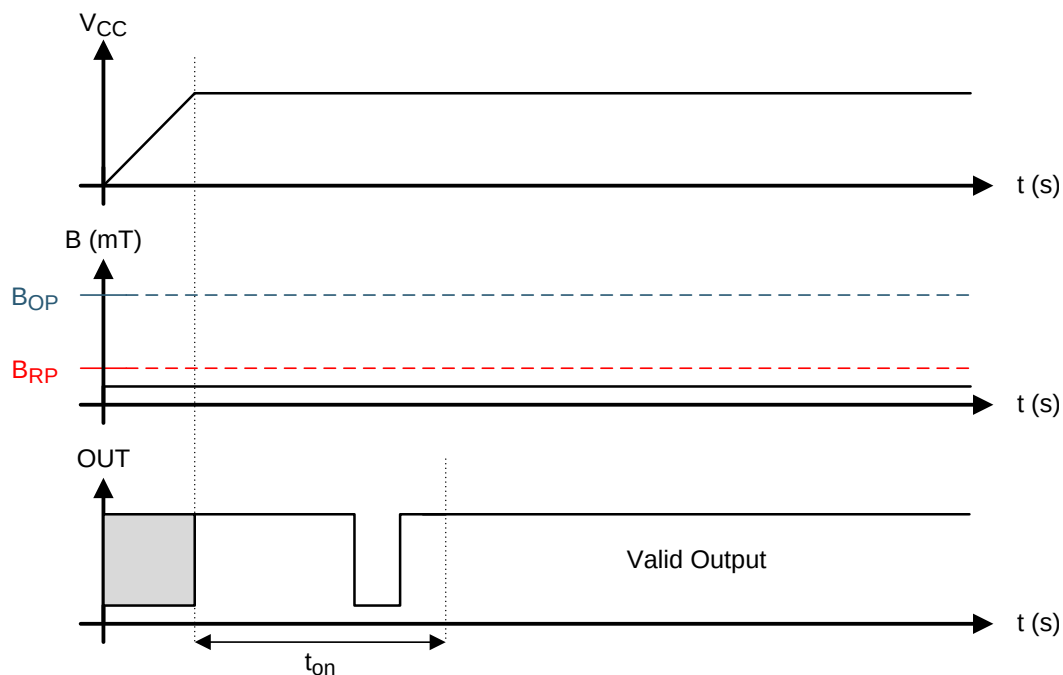
## Feature Description (continued)

### 8.3.3 Power-On Time

After applying  $V_{CC}$  to the DRV5033-Q1 device,  $t_{on}$  must elapse before the OUT pin is valid. During the power-up sequence, the output is Hi-Z. A pulse as shown in Figure 13 and Figure 14 occurs at the end of  $t_{on}$ . This pulse can allow the host processor to determine when the DRV5033-Q1 output is valid after startup. In Case 1 (Figure 13) and Case 2 (Figure 14), the output is defined assuming a constant magnetic field  $B > B_{OP}$  and  $B < B_{RP}$ .



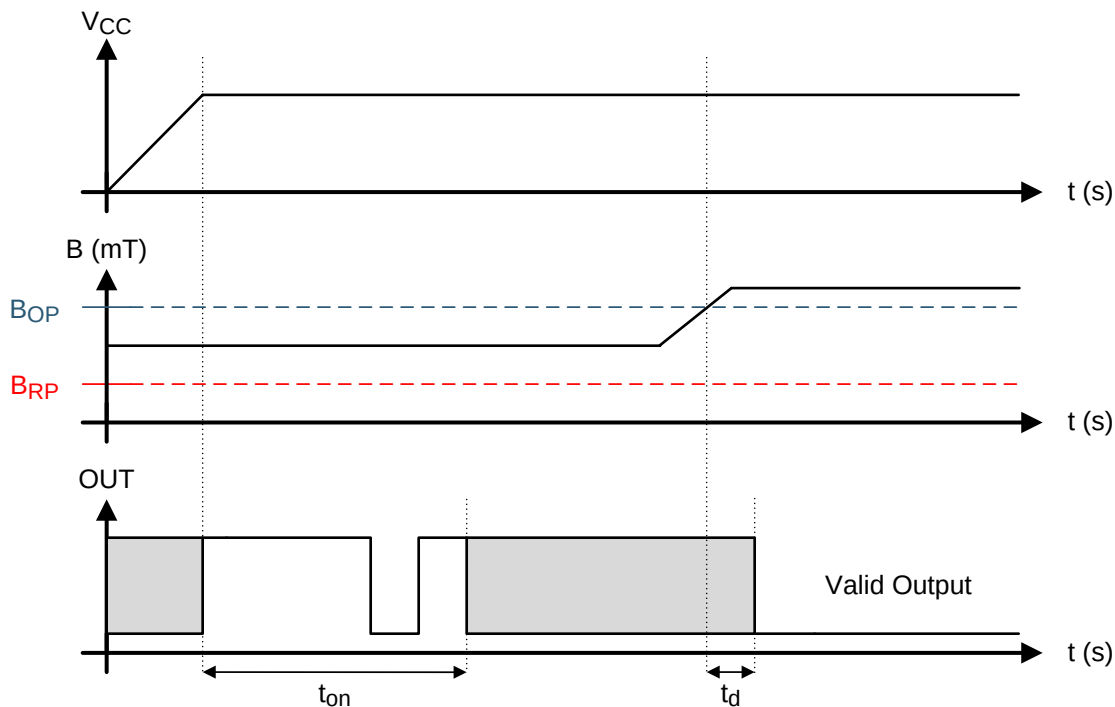
**Figure 13. Case 1: Power On When  $B > B_{OP}$**



**Figure 14. Case 2: Power On When  $B < B_{RP}$**

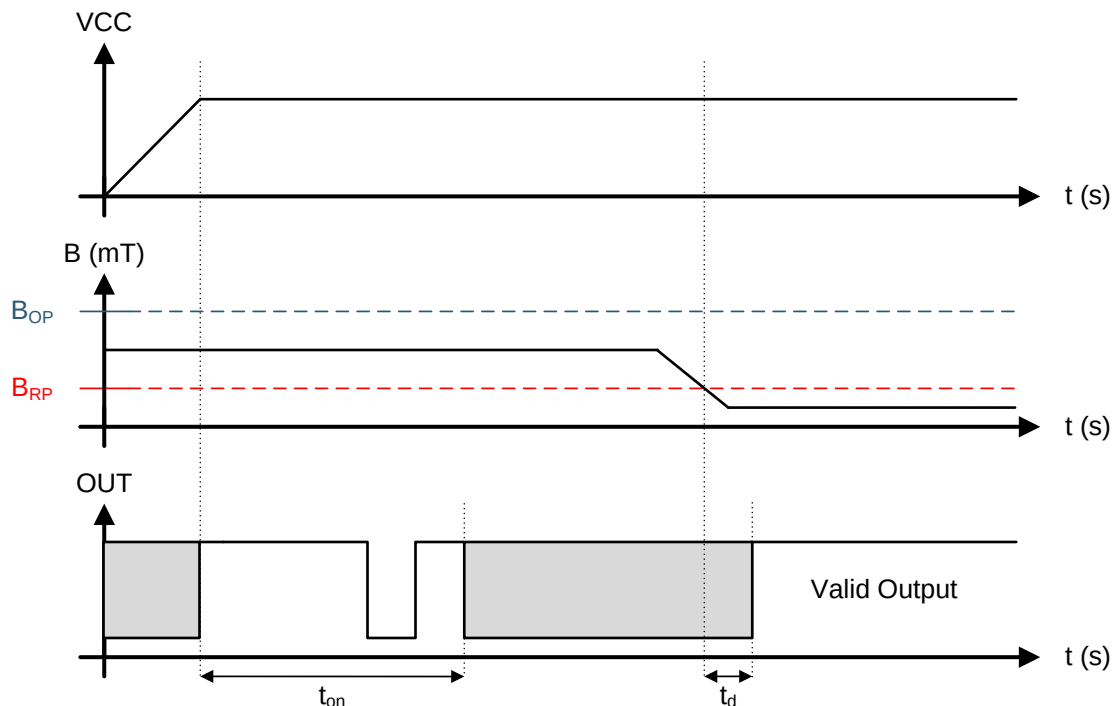
## Feature Description (continued)

If the device is powered on with the magnetic field strength  $B_{RP} < B < B_{OP}$ , then the device output is indeterminate and can either be Hi-Z or pulled low. During the power-up sequence, the output is held Hi-Z until  $t_{on}$  has elapsed. At the end of  $t_{on}$ , a pulse is given on the OUT pin to indicate that  $t_{on}$  has elapsed. After  $t_{on}$ , if the magnetic field changes such that  $B_{OP} < B$ , the output is released. Case 3 (Figure 15) and Case 4 (Figure 16) show examples of this behavior.



**Figure 15. Case 3: Power On When  $B_{RP} < B < B_{OP}$ , Followed by  $B > B_{OP}$**

## Feature Description (continued)



**Figure 16. Case 4: Power On When  $B_{RP} < B < B_{OP}$ , Followed by  $B < B_{RP}$**

### 8.3.4 Output Stage

The DRV5033-Q1 output stage uses an open-drain NMOS, and it is rated to sink up to 30 mA of current. For proper operation, calculate the value of the pullup resistor R1 using [Equation 1](#).

$$\frac{V_{ref \text{ max}}}{30 \text{ mA}} \leq R1 \leq \frac{V_{ref \text{ min}}}{100 \mu\text{A}} \quad (1)$$

The size of R1 is a tradeoff between the OUT rise time and the current when OUT is pulled low. A lower current is generally better, however faster transitions and bandwidth require a smaller resistor for faster switching.

In addition, ensure that the value of  $R1 > 500 \Omega$  to ensure the output driver can pull the OUT pin close to GND.

#### NOTE

$V_{ref}$  is not restricted to  $V_{CC}$ . The allowable voltage range of this pin is specified in the [Absolute Maximum Ratings](#).

## Feature Description (continued)

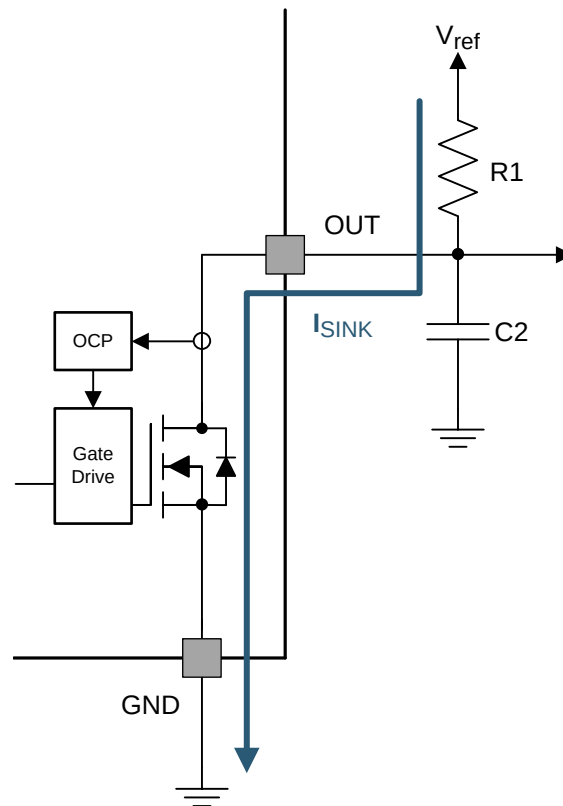


Figure 17.

Select a value for C2 based on the system bandwidth specifications as shown in [Equation 2](#).

$$2 \times f_{BW} \text{ (Hz)} < \frac{1}{2\pi \times R1 \times C2} \quad (2)$$

Most applications do not require this C2 filtering capacitor.

## Feature Description (continued)

### 8.3.5 Protection Circuits

The DRV5033-Q1 device is fully protected against overcurrent and reverse-supply conditions.

#### 8.3.5.1 Overcurrent Protection (OCP)

An analog current-limit circuit limits the current through the FET. The driver current is clamped to  $I_{OCP}$ . During this clamping, the  $r_{DS(on)}$  of the output FET is increased from the nominal value.

#### 8.3.5.2 Load Dump Protection

The DRV5033-Q1 device operates at DC  $V_{CC}$  conditions up to 38 V nominally, and can additionally withstand  $V_{CC} = 40$  V. No current-limiting series resistor is required for this protection.

#### 8.3.5.3 Reverse Supply Protection

The DRV5033-Q1 device is protected in the event that the  $V_{CC}$  pin and the GND pin are reversed (up to  $-22$  V).

#### NOTE

In a reverse supply condition, the OUT pin reverse-current must not exceed the ratings specified in the [Absolute Maximum Ratings](#).

**Table 1.**

| FAULT              | CONDITION                            | DEVICE    | DESCRIPTION                                  | RECOVERY                   |
|--------------------|--------------------------------------|-----------|----------------------------------------------|----------------------------|
| FET overload (OCP) | $I_{SINK} \geq I_{OCP}$              | Operating | Output current is clamped to $I_{OCP}$       | $I_O < I_{OCP}$            |
| Load dump          | $38\text{ V} < V_{CC} < 40\text{ V}$ | Operating | Device will operate for a transient duration | $V_{CC} \leq 38\text{ V}$  |
| Reverse supply     | $-22\text{ V} < V_{CC} < 0\text{ V}$ | Disabled  | Device will survive this condition           | $V_{CC} \geq 2.7\text{ V}$ |

## 8.4 Device Functional Modes

The DRV5033-Q1 device is active only when  $V_{CC}$  is between 2.7 and 38 V.

When a reverse supply condition exists, the device is inactive.

## 9 Application and Implementation

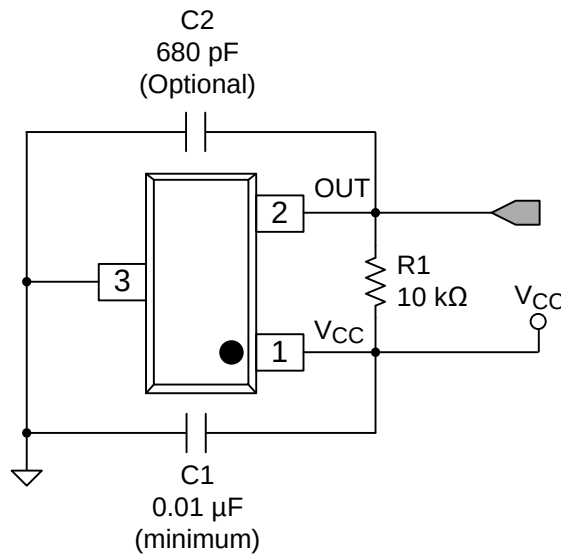
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The DRV5033-Q1 device is used in magnetic-field sensing applications.

### 9.2 Typical Application



**Figure 18. Typical Application Circuit**

#### 9.2.1 Design Requirements

For this design example, use the parameters listed in [Table 2](#) as the input parameters.

**Table 2. Design Parameters**

| DESIGN PARAMETER | REFERENCE | EXAMPLE VALUE |
|------------------|-----------|---------------|
| Supply voltage   | $V_{CC}$  | 3.2 to 3.4 V  |
| System bandwidth | $f_{BW}$  | 10 kHz        |

#### 9.2.2 Detailed Design Procedure

**Table 3. External Components**

| COMPONENT | PIN 1    | PIN 2              | RECOMMENDED                                              |
|-----------|----------|--------------------|----------------------------------------------------------|
| C1        | $V_{CC}$ | GND                | A 0.01-μF (minimum) ceramic capacitor rated for $V_{CC}$ |
| C2        | OUT      | GND                | <b>Optional:</b> Place a ceramic capacitor to GND        |
| R1        | OUT      | REF <sup>(1)</sup> | Requires a resistor pullup                               |

(1) REF is not a pin on the DRV5033-Q1 device, but a REF supply-voltage pullup is required for the OUT pin; the OUT pin may be pulled up to  $V_{CC}$ .

### 9.2.2.1 Configuration Example

In a 3.3-V system,  $3.2\text{ V} \leq V_{\text{ref}} \leq 3.4\text{ V}$ . Use [Equation 3](#) to calculate the allowable range for R1.

$$\frac{V_{\text{ref max}}}{30\text{ mA}} \leq R1 \leq \frac{V_{\text{ref min}}}{100\text{ }\mu\text{A}} \quad (3)$$

For this design example, use [Equation 4](#) to calculate the allowable range of R1.

$$\frac{3.4\text{ V}}{30\text{ mA}} \leq R1 \leq \frac{3.2\text{ V}}{100\text{ }\mu\text{A}} \quad (4)$$

Therefore:

$$113\text{ }\Omega \leq R1 \leq 32\text{ k}\Omega \quad (5)$$

After finding the allowable range of R1 ([Equation 5](#)), select a value between 500  $\Omega$  and 32 k $\Omega$  for R1.

Assuming a system bandwidth of 10 kHz, use [Equation 6](#) to calculate the value of C2.

$$2 \times f_{\text{BW}}\text{ (Hz)} < \frac{1}{2\pi \times R1 \times C2} \quad (6)$$

For this design example, use [Equation 7](#) to calculate the value of C2.

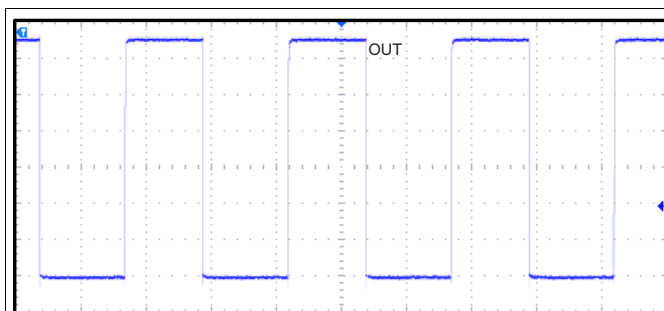
$$2 \times 10\text{ kHz} < \frac{1}{2\pi \times R1 \times C2} \quad (7)$$

An R1 value of 10 k $\Omega$  and a C2 value less than 820 pF satisfy the requirement for a 10-kHz system bandwidth.

A selection of R1 = 10 k $\Omega$  and C2 = 680 pF would cause a low-pass filter with a corner frequency of 23.4 kHz.



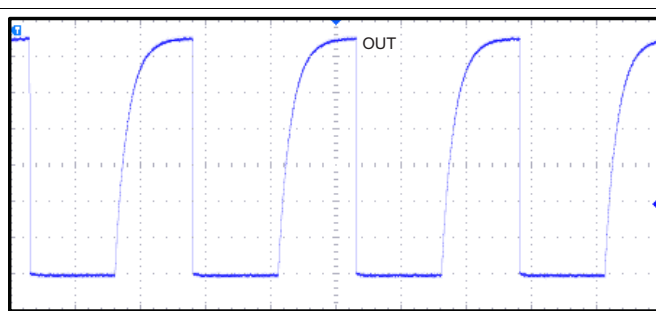
### 9.2.3 Application Curves



R1 = 10 kΩ pullup

No C2

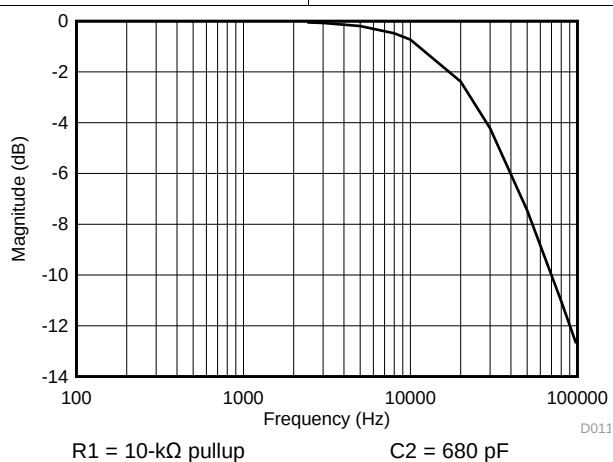
**Figure 19. 10-kHz Switching Magnetic Field**



R1 = 10-kΩ pullup

C2 = 680 pF

**Figure 20. 10-kHz Switching Magnetic Field**



R1 = 10-kΩ pullup

C2 = 680 pF

**Figure 21. Low-Pass Filtering**

## 10 Power Supply Recommendations

The DRV5033-Q1 device is designed to operate from an input voltage supply (VM) range between 2.7 and 38 V. A 0.01-μF (minimum) ceramic capacitor rated for  $V_{CC}$  must be placed as close to the DRV5033-Q1 device as possible.

## 11 Device and Documentation Support

### 11.1 Device Support

#### 11.1.1 Device Nomenclature

Figure 22 shows a legend for reading the complete device name for and DRV5033-Q1 device.

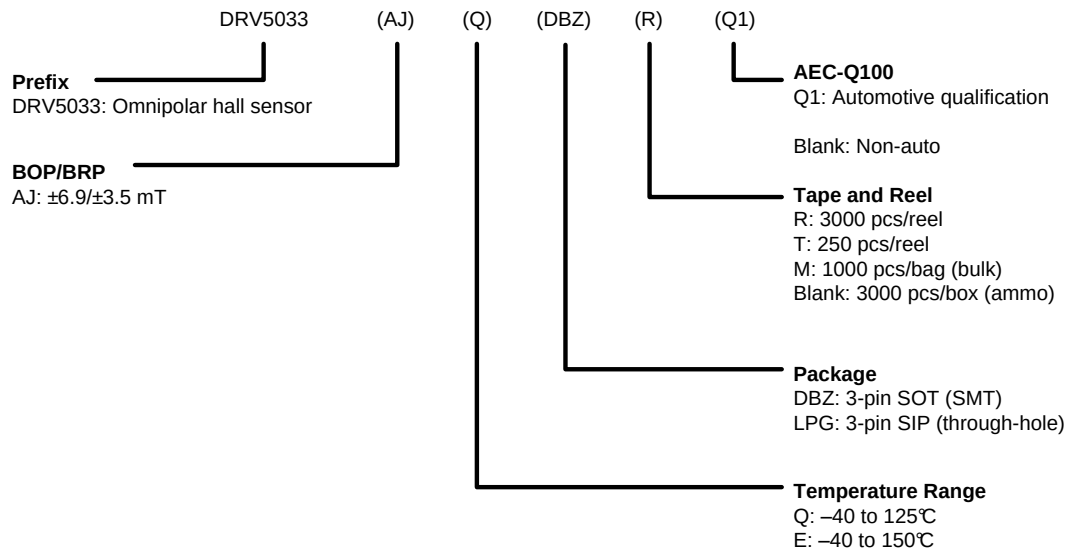


Figure 22. Device Nomenclature

#### 11.1.2 Device Markings

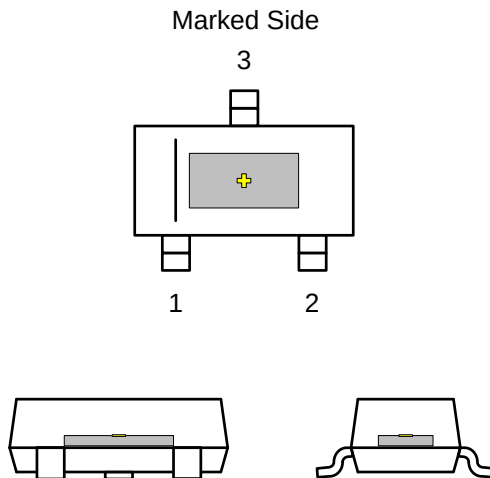


Figure 23. SOT-23 (DBZ) Package

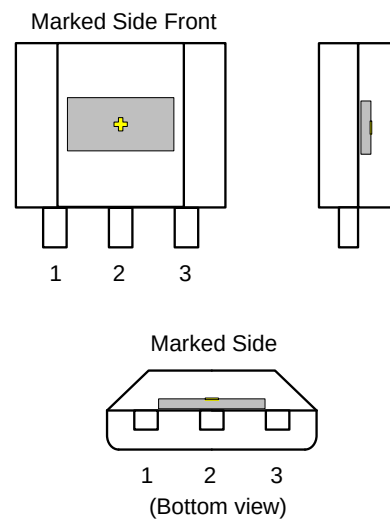


Figure 24. SIP (LPG) Package

✚ indicates the Hall effect sensor (not to scale). The Hall element is located in the center of the package with a tolerance of  $\pm 100$   $\mu$ m. The height of the Hall element from the bottom of the package is 0.7 mm  $\pm 50$   $\mu$ m in the DBZ package and 0.987 mm  $\pm 50$   $\mu$ m in the LPG package.

## 11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

## Community Resources (continued)

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### 11.3 Trademarks

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All other trademarks are the property of their respective owners.

### 11.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| DRV5033AJEDBZRQ1 | ACTIVE        | SOT-23       | DBZ                | 3    | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 150   | +QJAJ                   | <a href="#">Samples</a> |
| DRV5033AJEDBZTQ1 | ACTIVE        | SOT-23       | DBZ                | 3    | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 150   | +QJAJ                   | <a href="#">Samples</a> |
| DRV5033AJELPGMQ1 | ACTIVE        | TO-92        | LPG                | 3    | 3000           | Green (RoHS<br>& no Sb/Br) | CU SN                   | N / A for Pkg Type   | -40 to 150   | +QJAJ                   | <a href="#">Samples</a> |
| DRV5033AJELPGQ1  | ACTIVE        | TO-92        | LPG                | 3    | 1000           | Green (RoHS<br>& no Sb/Br) | CU SN                   | N / A for Pkg Type   | -40 to 150   | +QJAJ                   | <a href="#">Samples</a> |
| DRV5033AJQDBZRQ1 | ACTIVE        | SOT-23       | DBZ                | 3    | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | +QKAJ                   | <a href="#">Samples</a> |
| DRV5033AJQDBZTQ1 | ACTIVE        | SOT-23       | DBZ                | 3    | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | +QKAJ                   | <a href="#">Samples</a> |
| DRV5033AJQLPGMQ1 | ACTIVE        | TO-92        | LPG                | 3    | 3000           | Green (RoHS<br>& no Sb/Br) | CU SN                   | N / A for Pkg Type   | -40 to 125   | +QKAJ                   | <a href="#">Samples</a> |
| DRV5033AJQLPGQ1  | ACTIVE        | TO-92        | LPG                | 3    | 1000           | Green (RoHS<br>& no Sb/Br) | CU SN                   | N / A for Pkg Type   | -40 to 125   | +QKAJ                   | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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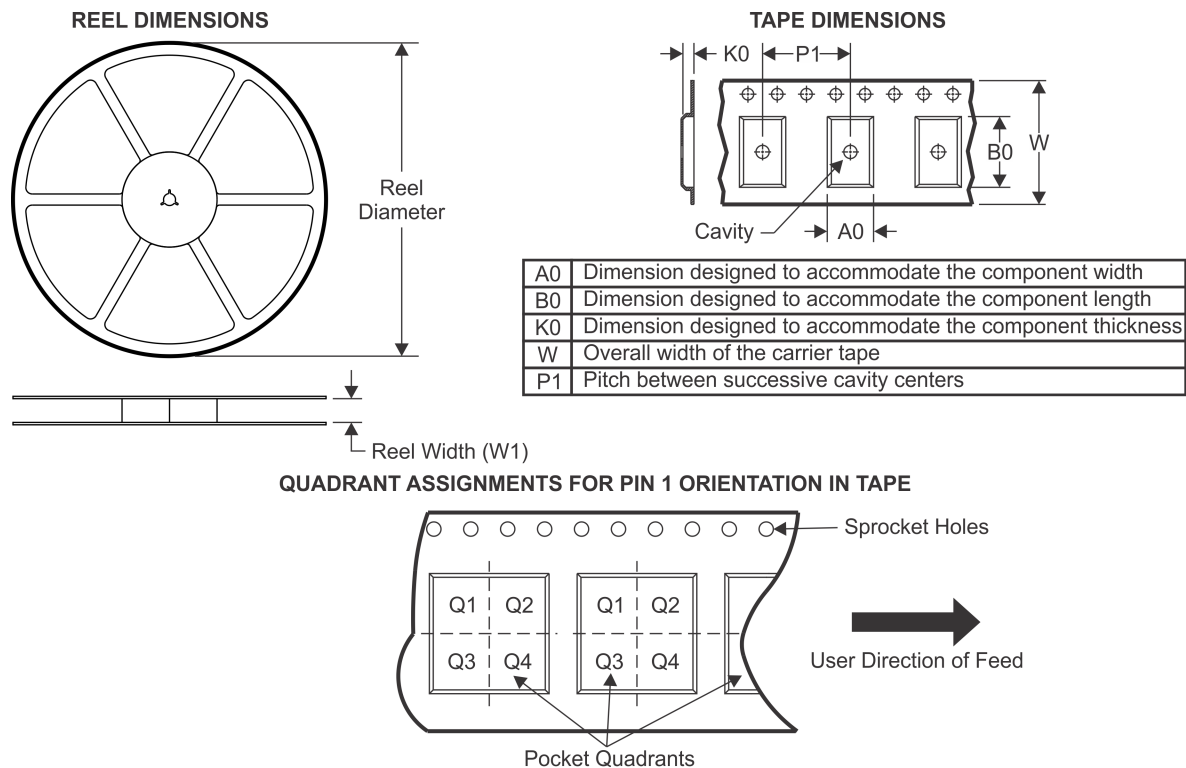
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF DRV5033-Q1 :**

- Catalog: [DRV5033](#)

NOTE: Qualified Version Definitions:

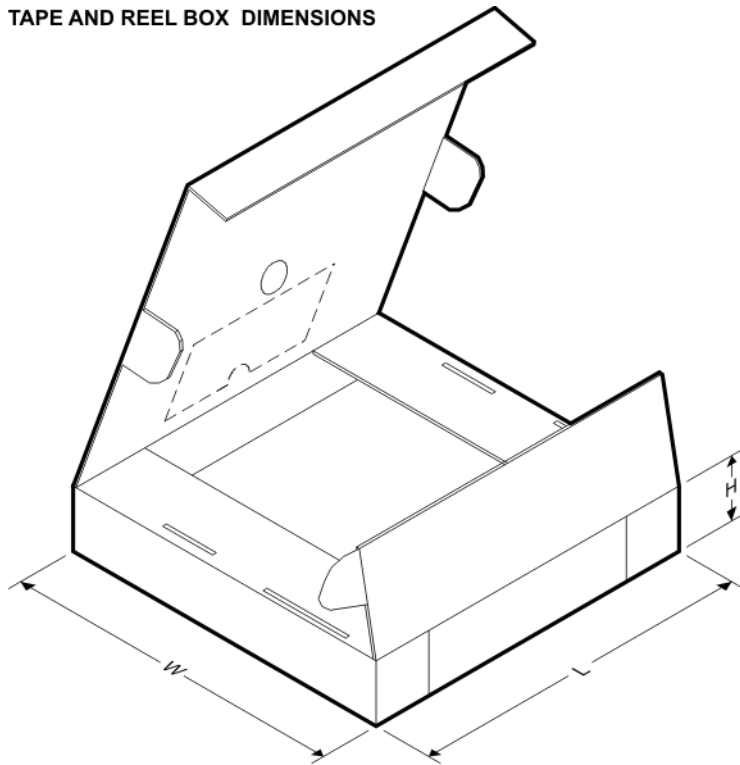
- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

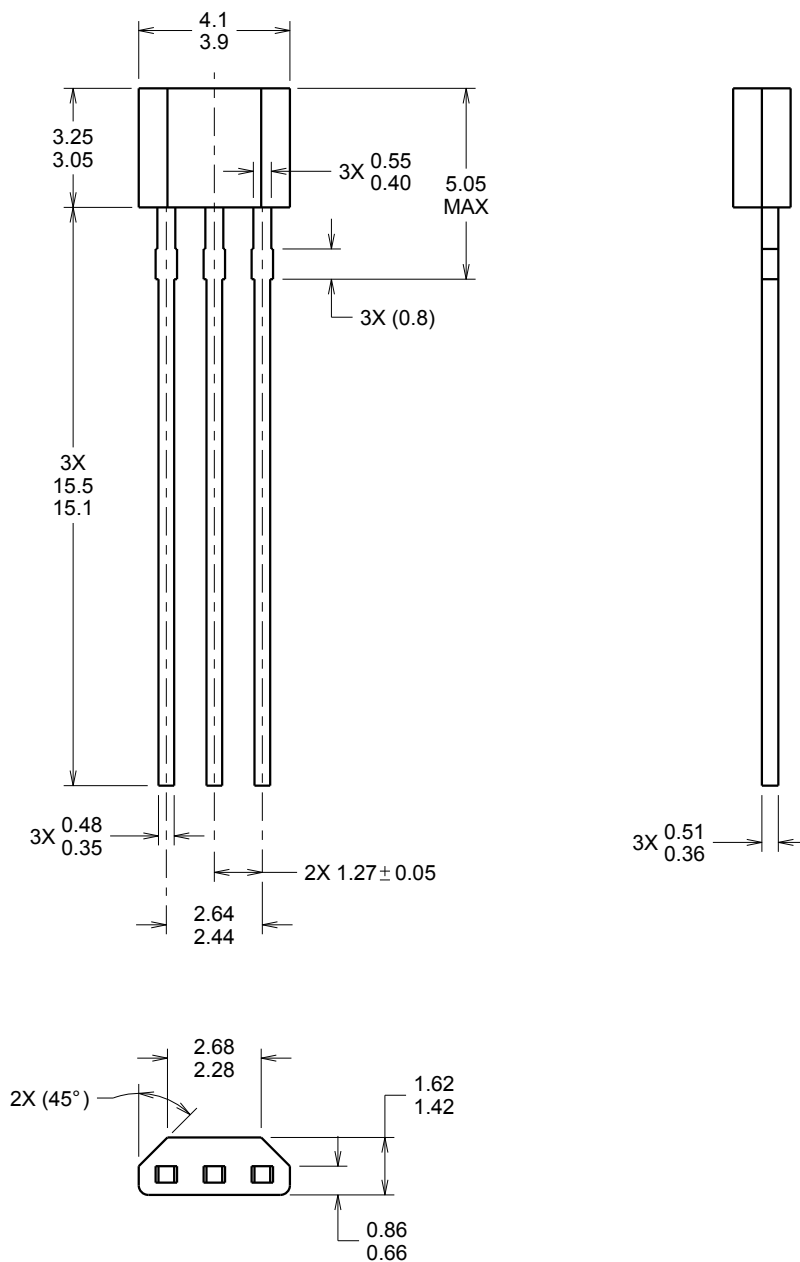
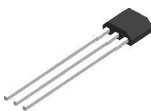
| Device           | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| DRV5033AJEDBZRQ1 | SOT-23       | DBZ             | 3    | 3000 | 180.0              | 8.4                | 3.15    | 2.77    | 1.22    | 4.0     | 8.0    | Q3            |
| DRV5033AJEDBZTQ1 | SOT-23       | DBZ             | 3    | 250  | 180.0              | 8.4                | 3.15    | 2.77    | 1.22    | 4.0     | 8.0    | Q3            |
| DRV5033AJQDBZRQ1 | SOT-23       | DBZ             | 3    | 3000 | 180.0              | 8.4                | 3.15    | 2.77    | 1.22    | 4.0     | 8.0    | Q3            |
| DRV5033AJQDBZTQ1 | SOT-23       | DBZ             | 3    | 250  | 180.0              | 8.4                | 3.15    | 2.77    | 1.22    | 4.0     | 8.0    | Q3            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| DRV5033AJEDBZRQ1 | SOT-23       | DBZ             | 3    | 3000 | 202.0       | 201.0      | 28.0        |
| DRV5033AJEDBZTQ1 | SOT-23       | DBZ             | 3    | 250  | 202.0       | 201.0      | 28.0        |
| DRV5033AJQDBZRQ1 | SOT-23       | DBZ             | 3    | 3000 | 202.0       | 201.0      | 28.0        |
| DRV5033AJQDBZTQ1 | SOT-23       | DBZ             | 3    | 250  | 202.0       | 201.0      | 28.0        |



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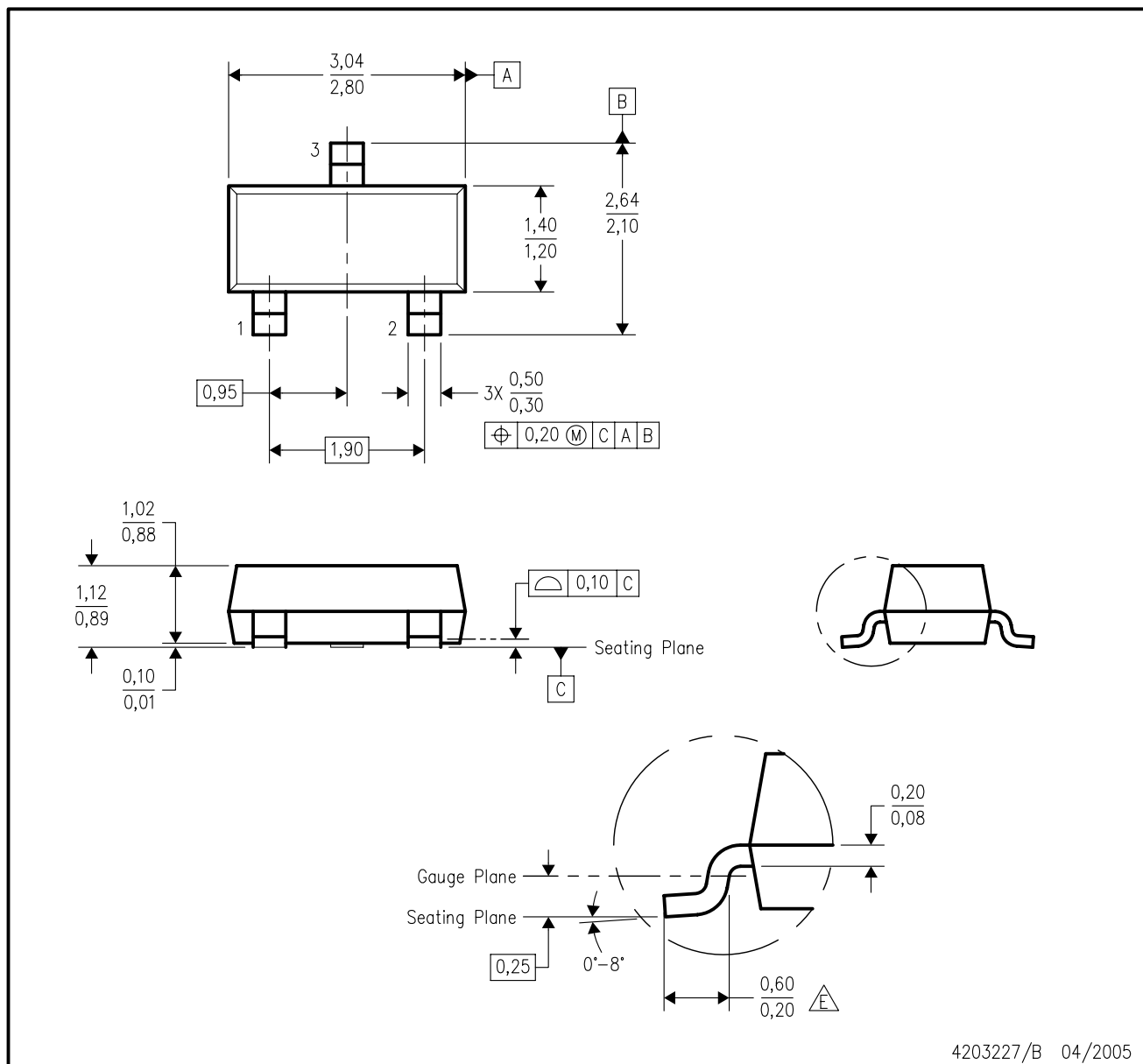
## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Lead dimensions are inclusive of plating.
  - D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
  - Falls within JEDEC TO-236 variation AB, except minimum foot length.

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|------------------------------|--------------------------------------------------------------------------------------|
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| Data Converters              | <a href="http://dataconverter.ti.com">dataconverter.ti.com</a>                       |
| DLP® Products                | <a href="http://www.dlp.com">www.dlp.com</a>                                         |
| DSP                          | <a href="http://dsp.ti.com">dsp.ti.com</a>                                           |
| Clocks and Timers            | <a href="http://www.ti.com/clocks">www.ti.com/clocks</a>                             |
| Interface                    | <a href="http://interface.ti.com">interface.ti.com</a>                               |
| Logic                        | <a href="http://logic.ti.com">logic.ti.com</a>                                       |
| Power Mgmt                   | <a href="http://power.ti.com">power.ti.com</a>                                       |
| Microcontrollers             | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a>                   |
| RFID                         | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
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### Applications

|                               |                                                                                          |
|-------------------------------|------------------------------------------------------------------------------------------|
| Automotive and Transportation | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.